

Vishay Siliconix

N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^{a, e}	Q _g (Typ.)			
20	0.0022 at V _{GS} = 10 V	90	82 nC			
30	0.0027 at V _{GS} = 4.5 V	90	02 110			

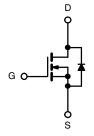
FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912





- OR-ing
- Server



Ordering Information: SUM90N03-2m2P-E3 (Lead (Pb)-free)

Top View

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	S ($T_A = 25 ^{\circ}C$, unle	ess otherwise no	ted)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		90 ^{a, e}		
Continuous Proin Current (T. – 175 °C)	T _C = 70 °C		90 ^e		
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	I _D	33 ^{b, c}	A	
	T _A = 70 °C		29.8 ^{b, c}		
Pulsed Drain Current	Pulsed Drain Current				
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	36		
Single Pulse Avalanche Energy	L=0.11IIII	E _{AS}	64.8	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	lo.	90 ^{a, e}	Α	
Continuous Source-Diam Diode Current	T _A = 25 °C	l _S	3.13 ^{b, c}		
	T _C = 25 °C		250 ^a		
Maximum Dawar Dissination	T _C = 70 °C	P _D	175	\Box w	
Maximum Power Dissipation	T _A = 25 °C	rD	3.75 ^{b, c}	vv	
	T _A = 70 °C		2.63 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	- °C/W		

Notes:

- a. Based on T_C = 25 °C.
 b. Surface mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 90 °C/W.
- e. Calculated based on maximum junction temperature. Package limitation current is 90 A.

Document Number: 74342 S12-0680-Rev. C, 26-Mar-12 For more information please contact: pmostechsupport@vishav.com

SUM90N03-2m2P

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SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min .	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		35		mV/°0	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 _D = 200 μ/τ		- 7.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.5		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Coto Voltago Droin Current	lana	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			Α	
	В	$V_{GS} = 10 \text{ V}, I_D = 32 \text{ A}$		0.0018	0.0022	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 29 \text{ A}$		0.0022	0.0027		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 32 A		160		S	
Dynamic ^b				•	•		
Input Capacitance	C _{iss}			12065			
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1725		pF	
Reverse Transfer Capacitance	C _{rss}			970			
Total Gate Charge		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 32 A		171	257	nC	
	Q_g			81.5	123		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 29 \text{ A}$		34			
Gate-Drain Charge	Q _{gd}			29			
Gate Resistance	R _g	f = 1 MHz		1.4	2.1	Ω	
Turn-On Delay Time	t _{d(on)}			18	27		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 0.555 \Omega$		11	17		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 27 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		70	105		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			55	83	ns	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{I} = 0.625 \Omega$		180	270		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 24 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		55	83		
Fall Time	t _f	Ç		12	18		
Drain-Source Body Diode Characteristic			L			l	
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			90		
Pulse Diode Forward Current ^a	I _{SM}				200	Α	
Body Diode Voltage	V _{SD}	I _S = 22 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	-		52	78	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			70.2	105	nC	
Reverse Recovery Fall Time	t _a	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		27			
Reverse Recovery Rise Time	t _b			25		ns	

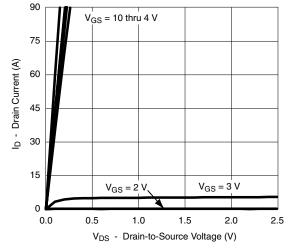
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

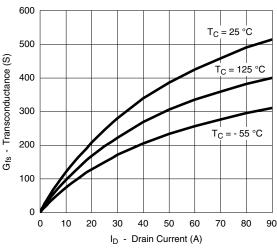
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



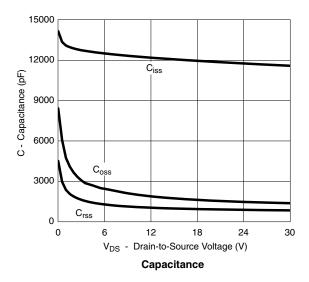
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

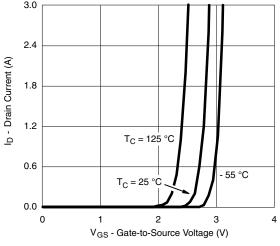


Output Characteristics

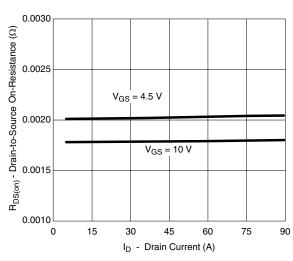


Transconductance

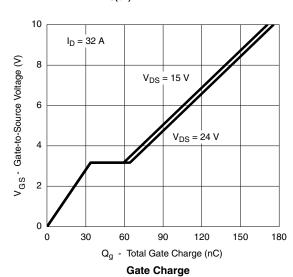




Transfer Characteristics

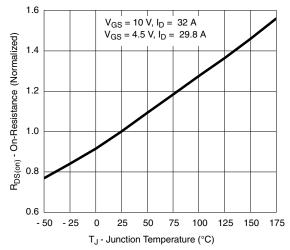


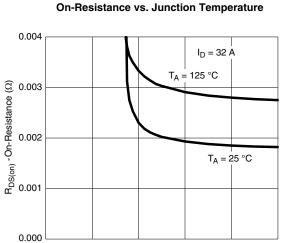
R_{DS(on)} vs. Drain Current



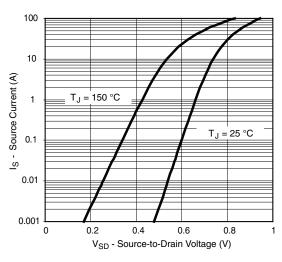
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

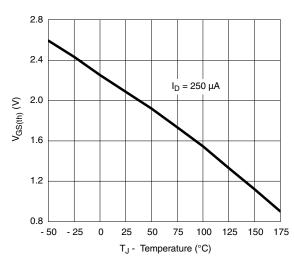




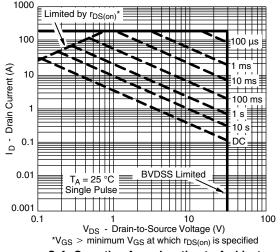
V_{GS} - Gate-to-Source Voltage (V) $R_{DS(on)}$ vs. V_{GS} vs. Temperature



Forward Diode Voltage vs. Temperature



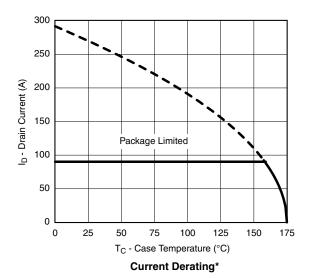
Threshold Voltage

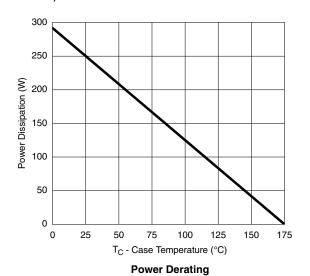


Safe Operating Area, Junction-to-Ambient

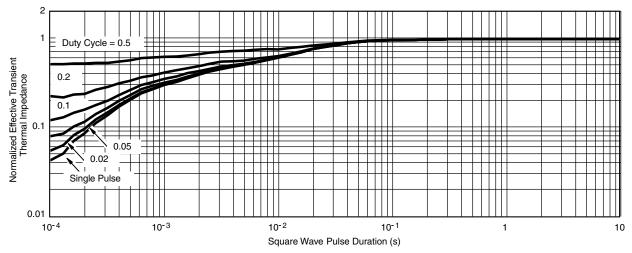


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





* The power dissipation P_D is based on $T_{J(max)}$ = 175 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

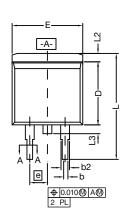


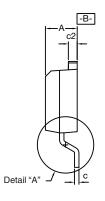
Normalized Thermal Transient Impedance, Junction-to-Case

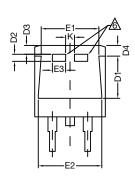
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TO-263 (D²PAK): 3-LEAD

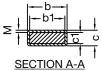








DETAIL A (ROTATED 90°)



_ - b1 , , ,	
≥ 	- -

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB. Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

6. This feature is for thick lead.

		INC	HES	MILLIMETERS		
DIM.		MIN.	MAX.	MIN.	MAX.	
Α		0.160	0.190	4.064	4.826	
b		0.020	0.039	0.508	0.990	
	b1	0.020	0.035	0.508	0.889	
b2		0.045	0.055	1.143	1.397	
-*	Thin lead	0.013	0.018	0.330	0.457	
C*	Thick lead	0.023	0.028	0.584	0.711	
c1	Thin lead	0.013	0.017	0.330	0.431	
CI	Thick lead	0.023	0.027	0.584	0.685	
	c2	0.045	0.055	1.143	1.397	
	D	0.340	0.380	8.636	9.652	
	D1	0.220	0.240	5.588	6.096	
D2		0.038	0.042	0.965	1.067	
D3		0.045	0.055	1.143	1.397	
	D4	0.044	0.052	1.118	1.321	
E		0.380	0.410	9.652	10.414	
E1		0.245	-	6.223	=	
E2		0.355	0.375	9.017	9.525	
E3		0.072	0.078	1.829	1.981	
е		0.100) BSC	2.54 BSC		
K		0.045	0.055	1.143	1.397	
L		0.575	0.625	14.605	15.875	
L1		0.090	0.110	2.286	2.794	
L2		0.040	0.055	1.016	1.397	
L3		0.050	0.070	1.270	1.778	
L4		0.010 BSC		0.254 BSC		
M		-	0.002	-	0.050	
ECN: T13-0707-Rev. K, 30-Sep-13						

DWG: 5843





RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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